

Preface

Dear Distinguished Authors and Guests,

It was a great pleasure to welcome all participants in the 2020 9th International Conference on Advanced Materials and Engineering Materials (ICAMEM 2020) held in Bangkok, Thailand 3-5, July, 2020.

Since the first ICAMEM in Shenyang, China (2011), a series of ICAMEM has been held in Asia: the 2nd, Beijing, China (2012), the 3rd, Singapore (2013), the 4th, Ningbo & Hong Kong, China (2014), the 5th, Hong Kong, China (2016), the 6th, Singapore (2017), the 7th, Bangkok, Thailand (2018), the 8th, Hong Kong, China (2019).

The aim of 9th ICAMEM2020 is to gather professors, researchers and scholars all over the world. ICAMEM2020 will provide leading academy and industry scientists a platform to communicate recent advances in Advanced Materials and Engineering Materials Research and an opportunity to establish multilateral collaborations.

The papers were selected after the peer-review process by conference committee members and international reviewers. The submitted papers were selected on the basis of originality, significance, and clarity for the purpose of the conference.

On behalf of the organizing committee, the editor would like to acknowledge the technical comments from the reviewers and thank all of the authors for their contributions to this proceeding book.

With our warmest regards,

Conference Organizing Chair
Prof. Peng-Sheng Wei
National Sun Yat-Sen University, Kaohsiung, Taiwan
April 24, 2020

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